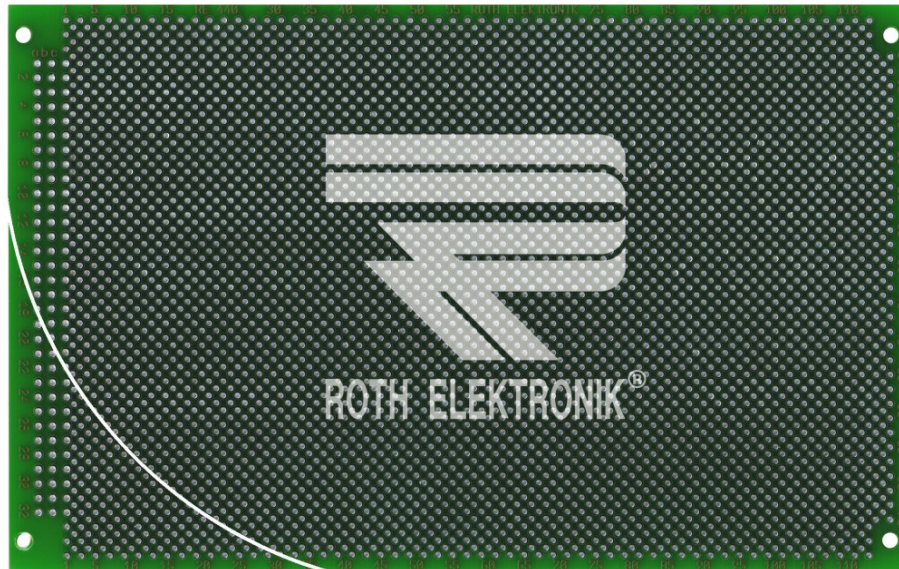


Prototyping Board



RE440-LF

- EPOXY fibre-glass FR4 1.50 mm double-sided 35 µm CU (pth)
- hot air leveling (HAL-leadfree)
- 4304 single-hole conductors 1.40 mm Ø
- hole dia 0.80 mm
- staggered hole grid 2.54 x 2.54 mm, thus duplication of the borings (interstitial)
- particularly appropriated for PGA sockets instaggered grid 2.54 x 2.54 mm
- connector 32 / 64 / 96 - channel
- DIN 41612 type C
- solder stop mask at the component and solder side
- working temperature max. 150° C.
- solder bath proof: 260° C. > 50 Sek.
- size 100 x 160 mm